

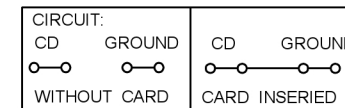
PCB LAYOUT

NOTES:

1. MATERIAL:
 - 1.1 Housing: HI-TEMP. PLASIC UL94V-0; Color Black.
 - 1.2 Terminal: Copper Alloy.
 - 1.3 Shell: SUS.
2. PLATING:
 - 2.1 Contact: Contact Area: Au G/F, Solder area: Matte tin
; Under plate Ni all over
 - 2.2 SHELL: Solder Area: Au G/F, Under plate Ni all over
 - 2.3 CD PIN: Contact Area: Au G/F, Under plate all over
3. SPECIALITY:
 - 3.1 Rated current: 1.0A
 - 3.2 Rated voltage: 30V
 - 3.3 Contact Resistance: 50mΩ MAX
 - 3.4 Insulation Resistance: 1000MΩ MIN 500V DC
 - 3.5 Dielectric withstanding voltage: 500V AC.
 - 3.6 Solder ability: 255±5 °C, 5±0.5s.
 - 3.7 Durability: 10000 Cycles Min.
 - 3.8 Operating condition: Temperature -40 °C ~ +85 °C;

Humidity 80% R.H MAX

Switch card state



Pin No.	MICRO SD
PIN1	DAT2 1P
PIN2	CD/DAT3 2P
PIN3	CMD 3P
PIN4	VDD 4P
PIN5	CLK 5P
PIN6	VSS 6P
PIN7	DAT0 7P
PIN8	DAT1 8P
PIN9	CARD DETECT

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	10	COPPER ALLOY	
①	Housing	1	HI-TEMP. PLASIC UL 94V-0	BLACK

广东星坤科技股份有限公司

MARK	DESCRIPTION	DATE	REVISED	APPROVED
Δ X				
Δ X				
Δ X				

文件工程章

REVISIONS	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
				ANGLAR ±5°
				L ≤ 4 ±0.2
				4 < L ≤ 16 ±0.3
				16 < L ≤ 63 ±0.4
				L > 63 ±0.5



DSND	SCALE: N/A	MODEL TYPE:
DWN	VIEW:	TF CARD CONN
CHKD	UNIT: mm/in	PART NO.:
APPD	SIZE: A4	DWG NO.: XKTF-001C
		WEIGHT
		SHEET 1/1
		REVISIO A0

XKB INDUSTRIAL PRECISION CO., LIMITED